

Method for producing conductive pattern of printed radioelectronic components, in which a metal resist is deposited onto the surface of the conductive pattern by electrodeposition. The copper is etched away from the open areas, and the metal resist is removed in a metal resist etching solution. Electrodeposition of the metal resist onto the surface of the conductive pattern is performed locally in the electrolyte, strictly in accordance with the layout of the conductive pattern. To apply the metal resist, an electrochemical 3D printer is used, programmed to move along a trajectory that creates a conductive pattern on the board, with the anode located inside the printer housing and the surface of the printed circuit board serving as the cathode.